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(12) **United States Design Patent**  
**Na et al.**

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(54) **BATTERY PROTECTION CIRCUIT MODULE PACKAGE**

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(51) **LOC (13) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/119**

(58) **Field of Classification Search**  
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CPC ..... H02H 7/18; H02J 7/0029; H01M 10/425;  
H01M 10/4257; H01M 10/48  
See application file for complete search history.

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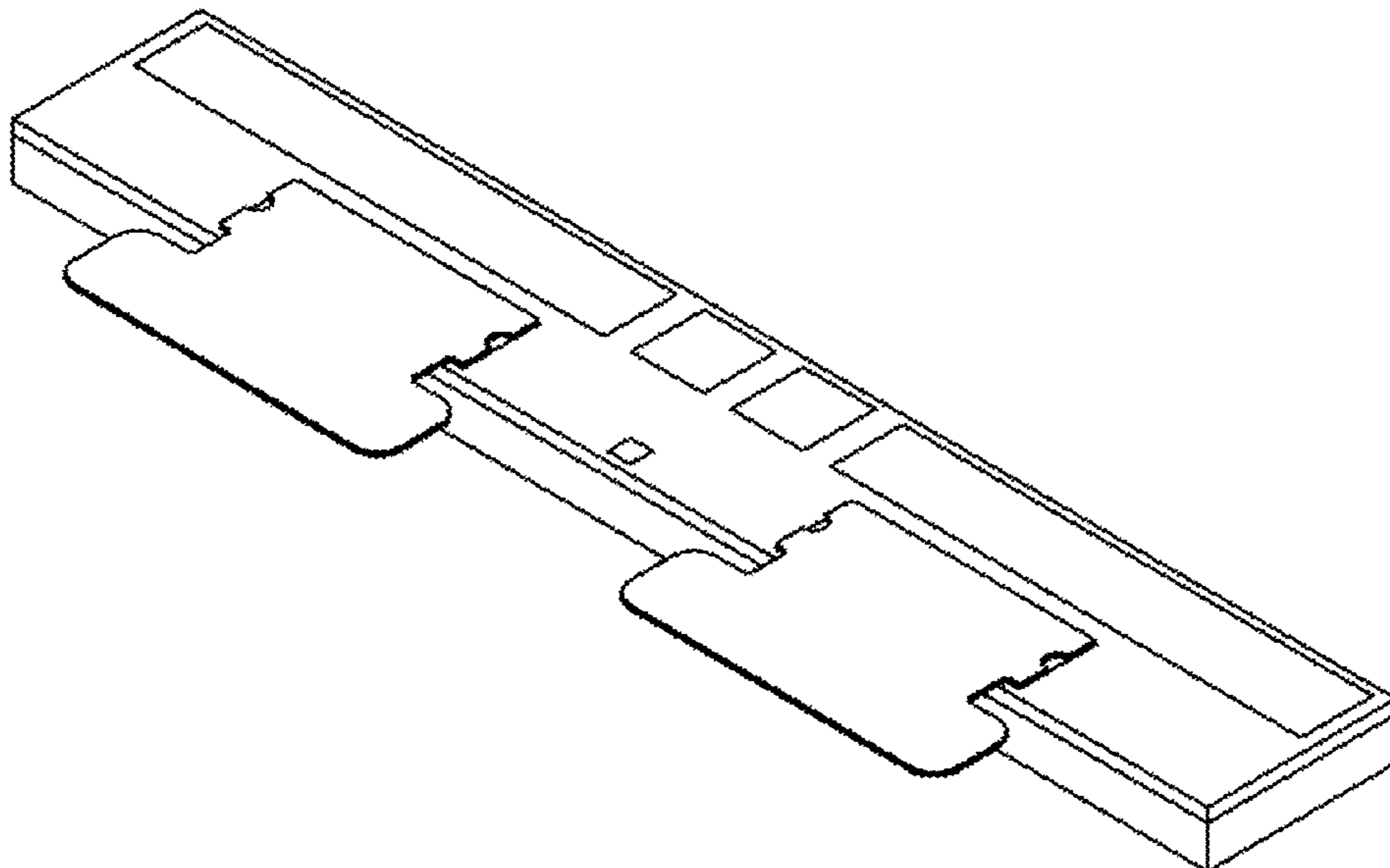
(57) **CLAIM**

We claim the ornamental design for a battery protection circuit module package, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a battery protection circuit module package showing our new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a rear elevational view thereof; FIG. 4 is a left side elevational view thereof; FIG. 5 is a right side elevational view thereof; FIG. 6 is a top plan view thereof; and, FIG. 7 is a bottom plan view thereof.

**1 Claim, 3 Drawing Sheets**



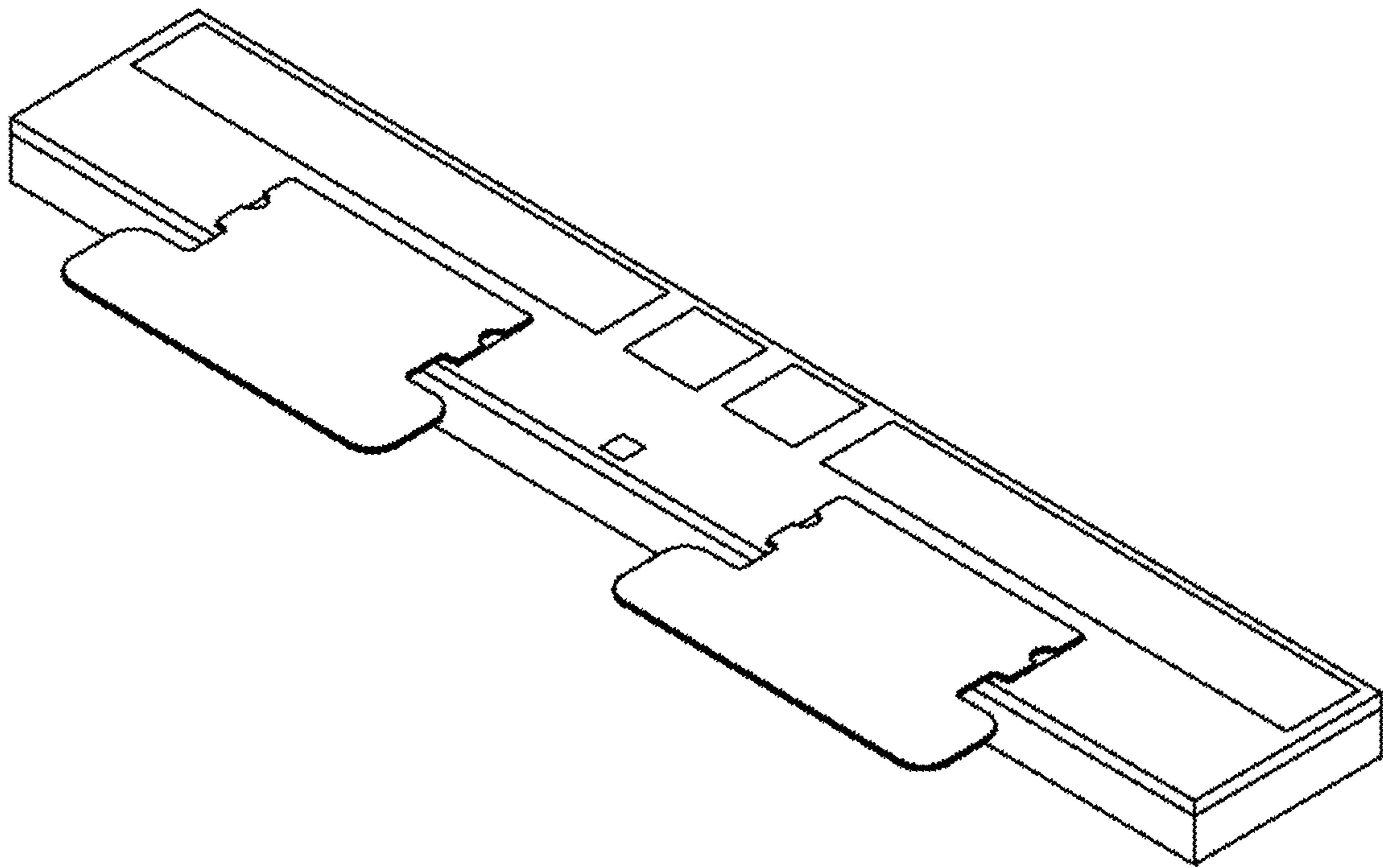
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**FIG. 1**



**FIG. 2**



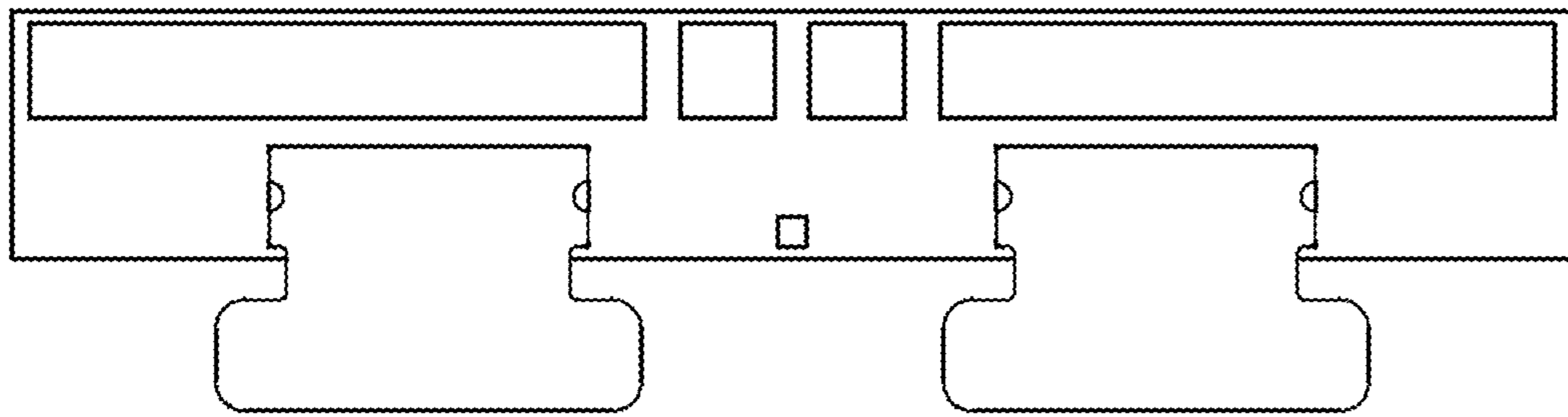
**FIG. 3**



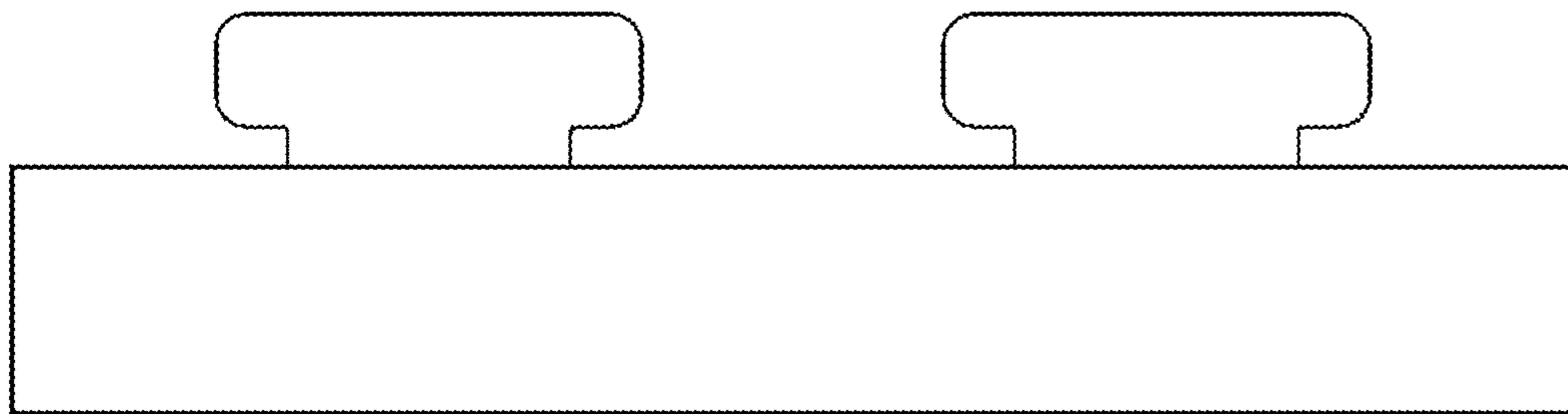
**FIG. 4**



**FIG. 5**



**FIG. 6**



**FIG. 7**